

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

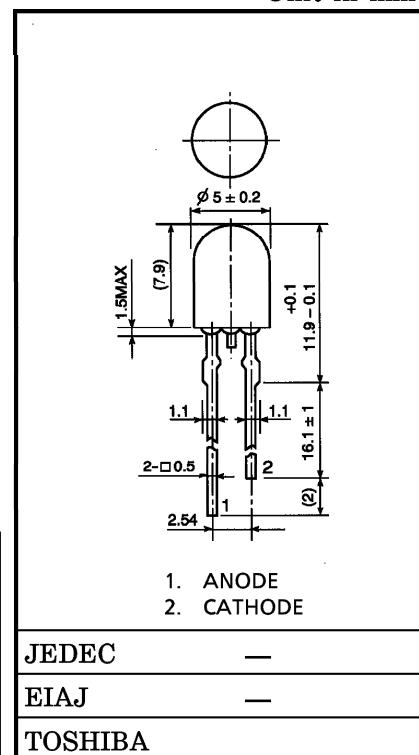
TLGD256

2 CHIP LED LAMP FOR MESSAGE BOARD

- 2 Chip Series Connection
- All Plastic Mold Type : Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission
Recommended Forward Current : $I_F = 15 \sim 20 \text{ mA (DC)}$
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Wide Rediation : Suitable for Message Board ($\pm 45 \text{ deg}$)

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I_F	30	mA
Reverse Voltage	V_R	8	V
Power Dissipation	P_D	170	mW
Operating Temperature Range	T_{opr}	$-30 \sim 85$	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	$-40 \sim 120$	$^\circ\text{C}$



Weight : 0.35g

ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V _F	I _F =20mA	—	4.3	5.4	V
Reverse Current	I _R	V _R =8V	—	—	5	μA
Luminous Intensity	I _V	I _F =20mA (Note)	85.0	150	—	mcd
TLGD256 (NP)			85.0	—	414	
Peak Emission Wave Length	λ _p	I _F =20mA	—	567	—	nm
Spectral Line Half Width	Δλ	I _F =20mA	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs ±15% additionary for guaranteed limits.

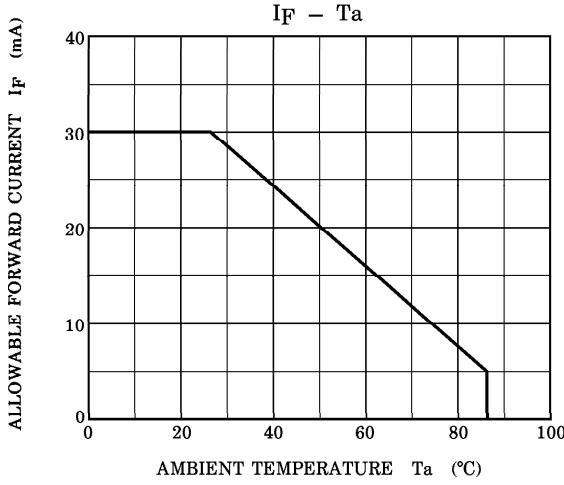
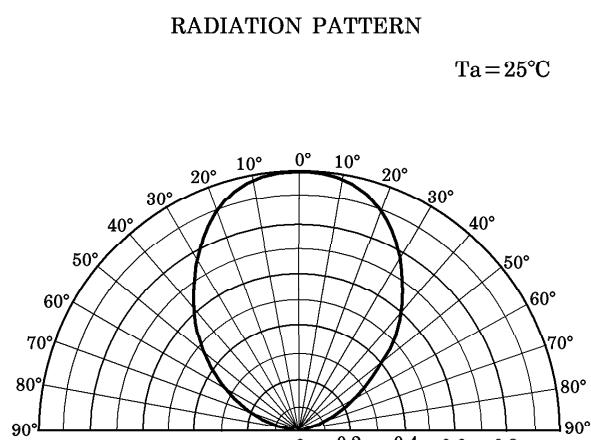
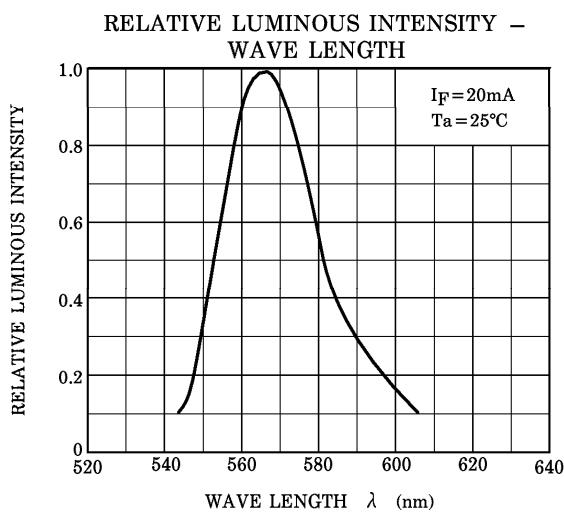
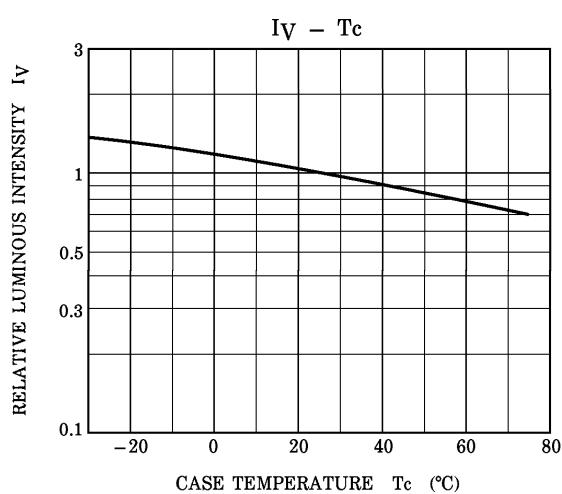
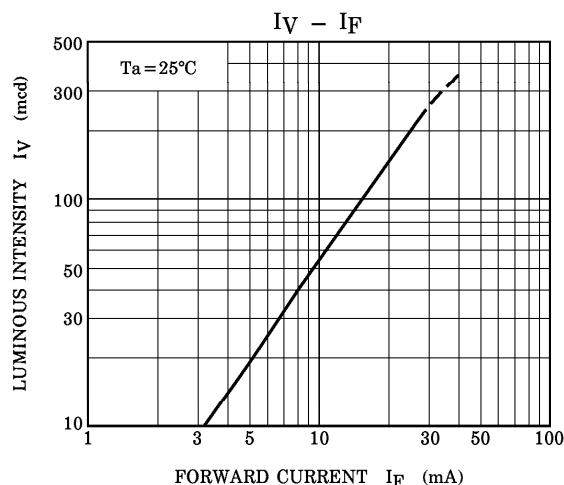
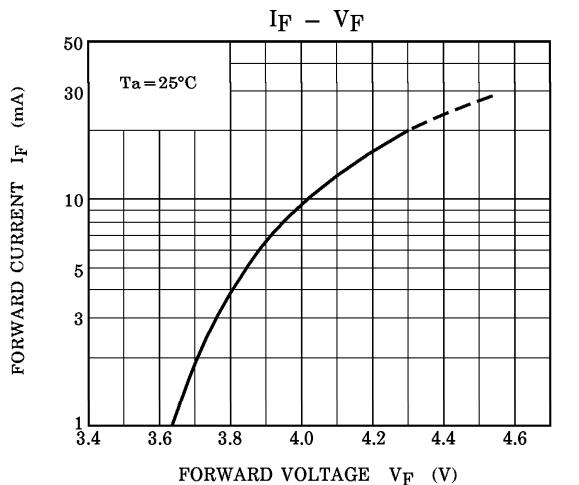
N : 100-200mcd P : 180-360mcd

Each rank products is classified by package unit, and (NP) includes N and P.

PRECAUTION

Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : below the Lead Stopper)
- If the lead is formed, the lead should be formed below the lead stopper without forming stress to the resin. Soldering should be performed after lead forming.



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